

SOT927-1

plastic low profile fine-pitch ball grid array package; 420 balls; body 13 x 13 x 1.1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA420
Package type industry code	LFBGA420
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-3-2006

Table 1. Package summary

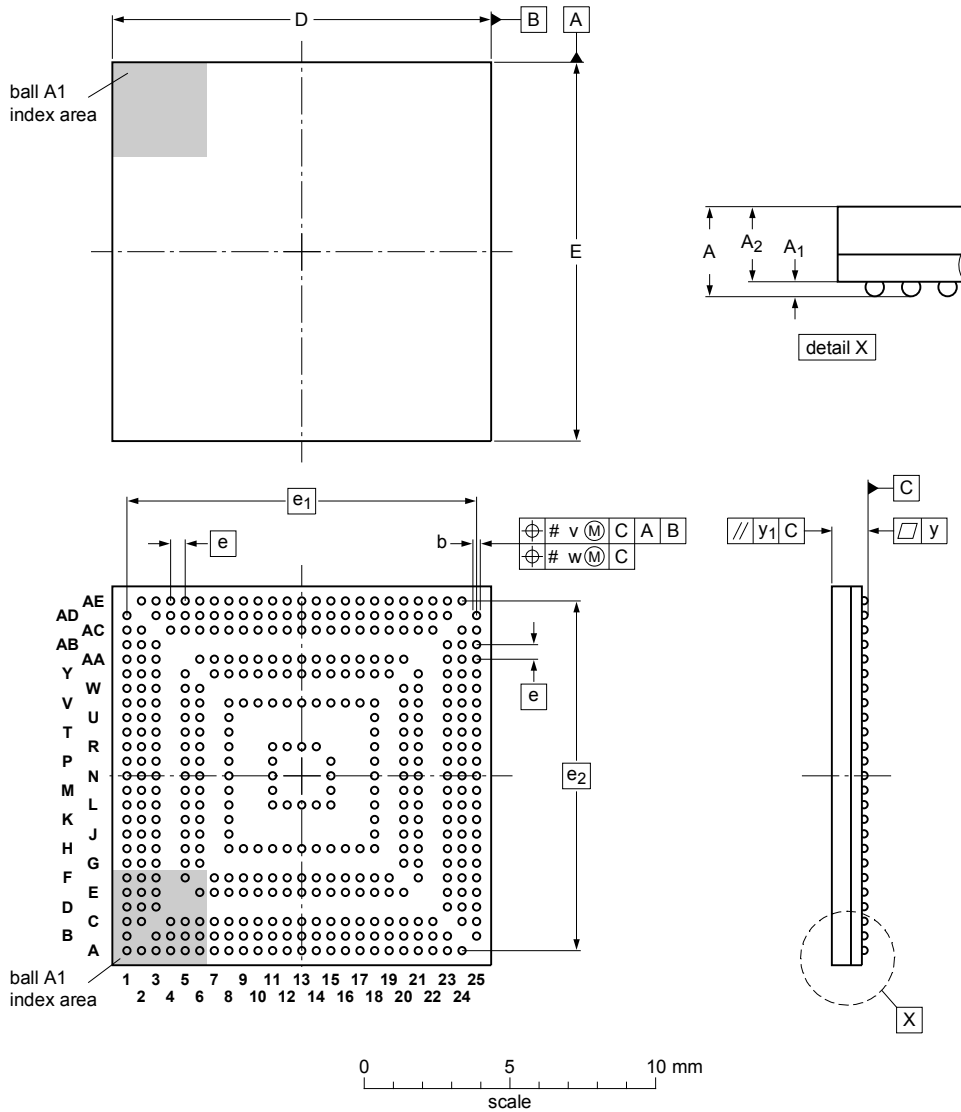
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	12.9	-	13	13.1	mm
E	package width	12.9	-	13	13.1	mm
A	seated height	[tbd]	-	1.4	1.4	mm
A ₂	package height	1.05	-	1.1	1.15	mm
n ₂	actual quantity of termination	-	-	420	-	



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2. Package outline

LFBGA420: plastic low profile fine-pitch ball grid array package; 420 balls; body 13 x 13 x 1.1 mm SOT927-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1.4	0.25 0.15	1.15 1.05	0.35 0.25	13.1 12.9	13.1 12.9	0.5	12	12	0.15	0.08	0.12	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT927-1		---				06-03-22 06-03-30

Fig. 1. Package outline LFBGA420 (SOT927-1)

3. Legal information

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